

(date)

His Royal Highness, Prince Mohamed Bolkiah  
Minister for Foreign Affairs  
Brunei Darussalam

Hon Ignacio Walker  
Minister of Foreign Affairs  
Republic of Chile

Hon Jim Sutton  
Minister for Trade Negotiations  
New Zealand

Dear Minister

I refer to the conclusion on this date of the Trans-Pacific Strategic Economic Partnership Agreement (the "Agreement") among Brunei Darussalam, Chile, New Zealand and Singapore and to the discussions in relation to Chapter 8 (*Technical Barriers to Trade*) of the Agreement. I have the honour to confirm the following understandings reached by Brunei Darussalam, Chile, New Zealand and Singapore during the course of the negotiations regarding the establishment of a Committee on Technical Barriers to Trade under the Agreement and the establishment of a work programme for this Committee.

The Committee on Technical Barriers to Trade in the first instance will comprise:

**Brunei Darussalam:** Ismail Hj Hamdan, Construction Planning and Research Unit, Ministry of Development;

**Chile:** Ana Maria Vallina, Director, Ministry of the Economy;

**New Zealand:** Sharon Anne Blaikie, Senior Adviser, Ministry of Economic Development;

**Singapore:** Ng Kim Neo, Consultant, Ministry of Trade and Industry.

Work programmes will initially be established on: electrical safety and electro magnetic compatibility of electrical and electronic equipment; grading programmes for the purposes of marketing beef; and shoe labelling. Trade facilitators, relevant regulators from New Zealand, Brunei Darussalam, Chile and Singapore, members of the SEP Committee on Technical Barriers to Trade

and any other expert as needed, will participate as required in these work programmes.

I would like to suggest that the work programmes on electrical safety and electromagnetic compatibility, beef grading and shoe labelling be initiated, via teleconferences of the trade facilitators, relevant regulators and stakeholders from each country, no later than November 2005.

If the above proposals are acceptable, I have the honour to propose that this letter and your confirmatory reply will constitute the understandings between our Governments on the initial future work programme for the Committee on Technical Barriers to Trade under the Agreement.

Yours sincerely

Lim Hng Kiang  
Minister of Trade and Industry  
Republic of Singapore